

WHAT IS CLAIMED IS:

1. A thin-film capacitor element comprising:
an insulative substrate having a via hole filled with a
5 conductive material;
a lower electrode;
a dielectric layer; and
an upper electrode; wherein the lower electrode, the
dielectric layer, and the upper electrode are successively
10 deposited in order on the insulative substrate, wherein
either one of the lower electrode and the upper electrode
connects to the end face of the conductive material; and
the dielectric layer is shaped like a ring to surround the
via hole.

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2. A thin-film capacitor element according to Claim 1,
wherein the dielectric layer is shaped like a ring with the via
hole as the center.

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3. A thin-film capacitor element according to Claim 1,
wherein the insulative substrate is made of low-temperature-
sintered ceramic.